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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/612,676	07/02/2003	Thomas C. Anthony	10014296-1	3426	
7	590 09/08/2005		EXAM	EXAMINER	
HEWLETT-PACKARD COMPANY			TRAN, LONG K		
Intellectual Pro	perty Administration				
P.O. Box 2724			ART UNIT	PAPER NUMBER	
Fort Collins, CO 80527-2400			2818		

DATE MAILED: 09/08/2005

Please find below and/or attached an Office communication concerning this application or proceeding.

			NY			
	Application No.	Applicant(s)	<i>)</i>			
	10/612,676	ANTHONY ET AL.				
Office Action Summary	Examiner	Art Unit				
	Long K. Tran	2818				
The MAILING DATE of this communication ap Period for Reply	pears on the cover sheet with the c	correspondence address				
A SHORTENED STATUTORY PERIOD FOR REPL THE MAILING DATE OF THIS COMMUNICATION. - Extensions of time may be available under the provisions of 37 CFR 1. after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a rep - If NO period for reply is specified above, the maximum statutory period - Failure to reply within the set or extended period for reply will, by statut Any reply received by the Office later than three months after the mailine earned patent term adjustment. See 37 CFR 1.704(b).	136(a). In no event, however, may a reply be tin ly within the statutory minimum of thirty (30) day will apply and will expire SIX (6) MONTHS from e, cause the application to become ABANDONE	nely filed s will be considered timely. the mailing date of this communication D (35 U.S.C. § 133).				
Status						
1) Responsive to communication(s) filed on 21 J	<u>uly 2005</u> .					
2a) This action is FINAL . 2b) ⊠ This	s action is non-final.					
3) Since this application is in condition for alloward closed in accordance with the practice under						
Disposition of Claims						
4) Claim(s) 1-12 and 18-32 is/are pending in the 4a) Of the above claim(s) 18 - 28 is/are withdrest 5) Claim(s) is/are allowed. 6) Claim(s) 1 - 12 and 29 - 32 is/are rejected. 7) Claim(s) is/are objected to. 8) Claim(s) are subject to restriction and/o	awn from consideration.					
Application Papers						
9) The specification is objected to by the Examina						
	0)☐ The drawing(s) filed on is/are: a)☐ accepted or b)☐ objected to by the Examiner.					
Applicant may not request that any objection to the						
Replacement drawing sheet(s) including the correct 11) The oath or declaration is objected to by the E).			
Priority under 35 U.S.C. § 119						
12) Acknowledgment is made of a claim for foreign a) All b) Some * c) None of: 1. Certified copies of the priority documen 2. Certified copies of the priority documen 3. Copies of the certified copies of the priority documen application from the International Burea * See the attached detailed Office action for a list	ts have been received. ts have been received in Applicat brity documents have been receive tu (PCT Rule 17.2(a)).	ion No ed in this National Stage				
	•					
Attachment(s)						
1) X Notice of References Cited (PTO-892)	4) Interview Summary					
2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08 Paper No(s)/Mail Date	Paper No(s)/Mail D 5) Notice of Informal F 6) Other:	ate Patent Application (PTO-152)				

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DETAILED ACTION

Continued Examination Under 37 CFR 1.114

1. A request for continued examination under 37 CFR 1.114, including the fee set forth in 37 CFR 1.17(e), was filed in this application after final rejection. Since this application is eligible for continued examination under 37 CFR 1.114, and the fee set forth in 37 CFR 1.17(e) has been timely paid, the finality of the previous Office action has been withdrawn pursuant to 37 CFR 1.114. Applicant's submission filed on June 07, 2005 has been entered.

Response to Amendment

- 2. This office action is in response to Amendment filed on June 07, 2005;
- 3. Claims 13 17 and 33 have been cancelled.
- 4. Claims 1, 29 and 30 have been amended.
- 5. Claims 18 28 have been withdrawn.
- 6. Claims 1 12 and 29 32 are presented for examination.
- 7. This is a new ground of rejection.

Claim Rejections - 35 USC § 103

- 8. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

- 9. Claims 1 12 and 29 32 are rejected under 35 U.S.C. 103(a) as being unpatentable over Rizzo et al. (US Patent Application Publication No. 2004/0000415) in view of Rostoker et al. (US Patent No. 5,389,556).
- 10. Regarding claim 1, Rizzo discloses a semiconductor device 5 (fig. 1, [0030]) comprising:

a first surface 17 (figs. 1-5 and 7-9) having memory chips 15 (figs. 2-4; only one shown; [0025], [0039] and [0003]) disposed thereon, the memory chips defining an exterior face 18 (figs. 1-5 and 7-9; [0026]) of the semiconductor device;

a second surface 21 (figs. 5 and 7 – 9; [0028]) opposite the exterior face 18; and A magnetically permeable shield layer 26 (figs. 7 – 9; [0032], [0033] and [0043]) extending over the entirety of the second surface 21.

However, as noted, Rizzo fails to disclose that the semiconductor device 5 including memory chips/dies 15 as a wafer having unseparated memory chips as claimed in the instant claim.

Nevertheless, at the time the invention was made, in order to form a plurality of identical chips/dies, one would form the identical chips/dies from a semiconductor wafer having unseparated chips before being cut into individual chip/die. One would do that because that was how one of the ordinary skills in the art would do also shown by Rostoker (column 1, lines 10 - 15).

Regarding claim **2**, Rizzo and Rostoker disclose the memory chips are separable from the memory wafer (Rizzo: [0039] and Rostoker, column 1, lines 15 – 17).

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Regarding claim **3**, Rizzo discloses memory chips 15 (figs. 1 – 2; [0025]) are MRAM.

Regarding claim 4, Rizzo discloses the memory chips 15 include multiple memory arrays having multiple memory cells 14 (figs. 1 - 5 and 7 - 9; [0025]).

Regarding claim 5, Rizzo discloses memory cells 14 are MRAM cells ([0025]).

Regarding claims **6** and **7**, Rizzo discloses the memory chips 15 include contact/bond pads (at the edges of the chips not shown; [0025], [0030] and [0049]) electrically accessible via the exterior face of the memory wafer.

Regarding claims **8** and **9**, Rizzo discloses the magnetically permeable shield layer 26 comprises a soft material selected from the group consisting of alloys of iron, alloys of nickel and alloys of cobalt ([0033]).

Regarding claim **10**, Rizzo et al. disclose the magnetically permeable shield layer 26 has a permeability of greater than 100 ([0042] and [0053]).

Regarding claim **11**, Rizzo et al. disclose the magnetically permeable shield layer has a coercivity of less than 10 Oersteds ([0043] and [0047]).

Regarding claim **12**, Rizzo et al. disclose the magnetically permeable shield layer is isotropic ([0053]).

11. Regarding claims **29** and **30**, Rizzo discloses a semiconductor device 5 (fig. 1, [0030]) comprising:

a first surface 17 (figs. 1-5 and 7-9) having memory chips 15 (figs. 2-4; only one shown; [0025], [0039] and [0003]) disposed thereon, the memory chips defining an exterior face 18 (figs. 1-5 and 7-9; [0026]) of the semiconductor device;

a second surface 21 (figs. 5 and 7 – 9; [0028]) opposite the exterior face 18; and A magnetically permeable shield layer 26 comprises a soft material selected from the group consisting of alloys of iron, alloys of nickel and alloys of cobalt (figs. 7 – 9; [0032], [0033] and [0043]) extending over the entirety of the second surface 21. *Note that the magnetically permeable shield layer 26 is considered means for protecting the memory chips from external or stray magnetic filed ([0003], [0006] and [0010]).*

Rizzo fails to disclose that the semiconductor device 5 including memory chips/dies 15 as a wafer having unseparated memory chips as claimed in the instant claim.

However, at the time the invention was made, in order to form a plurality of identical chips/dies, one would form the identical chips/dies from a semiconductor wafer having unseparated chips before being cut into individual chip/die. One would do that because that was how one of the ordinary skills in the art would do also shown by Rostoker (column 1, lines 10 - 15).

Regarding claim **31**, Rizzo et al. disclose the magnetically permeable shield layer 26 has a permeability of greater than 100 ([0042] and [0053]).

Regarding claim **32**, Rizzo et al. disclose the magnetically permeable shield layer has a coercivity of less than 10 Oersteds ([0043]).

Conclusion

12. The prior art made of record and not relied upon is considered pertinent to applicant's disclosure. Ray et al. (US Patent No. 6,921,965) discloses a memory device having a layer with high magnetic permeability for shielding the semiconductor device from stray or external magnetic fields similar to that of Rizzo et al. (US Patent

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Application Publication No. 2004/0000415) and Rostoker et al. (US Patent No.

5,389,556).

13. A shortened statutory period for response to this action is set to expire e (three)

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months and 0 (zero) day from the date of this letter. Failure to respond within the period

for response will cause the application to become abandoned (see MPEP 710.02 (b)).

14. Any inquiry concerning this communication or earlier communications from the

examiner should be directed to Long K. Tran whose telephone number is 571-272-

1797. The examiner can normally be reached on Mon-Thu.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's

supervisor, David Nelms can be reached on 571-272-1787. The fax phone number for

the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the

Patent Application Information Retrieval (PAIR) system. Status information for

published applications may be obtained from either Private PAIR or Public PAIR.

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For more information about the PAIR system, see http://pair-direct.uspto.gov. Should

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you have questions on access to the Private PAIR system, contact the Electronic

Business Center (EBC) at 866-217-9197 (toll-free).

LKT

August 22, 2005